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# 8-Mbit (512K words × 16-bit) Static RAM with Error-Correcting Code (ECC)

## Features

- Ultra-low standby current
  - Typical standby current: 5.5  $\mu$ A
  - Maximum standby current: 16  $\mu$ A
- High speed: 45 ns
- Voltage range: 2.2 V to 3.6 V
- Embedded Error-Correcting Code (ECC) for single-bit error correction
- 1.0 V data retention
- Transistor-transistor logic (TTL) compatible inputs and outputs
- Available in Pb-free 48-ball VFBGA and 48-pin TSOP I packages

## Functional Description

CY62157H is a high-performance CMOS low-power (MoBL) SRAM device with Embedded Error-Correcting Code. ECC logic can detect and correct single bit error in accessed location.

This device is offered in dual chip enable option. Dual chip enable devices are accessed by asserting both chip enable inputs –  $\overline{CE}_1$  as LOW and  $CE_2$  as HIGH.

Data writes are performed by asserting the Write Enable input ( $\overline{WE}$  LOW), and providing the data and address on device data ( $I/O_0$  through  $I/O_{15}$ ) and address ( $A_0$  through  $A_{18}$ ) pins respectively. The Byte High/Low Enable ( $\overline{BHE}$ ,  $\overline{BLE}$ ) inputs control byte writes, and write data on the corresponding I/O lines to the memory location specified.  $\overline{BHE}$  controls  $I/O_8$  through  $I/O_{15}$  and  $\overline{BLE}$  controls  $I/O_0$  through  $I/O_7$ .

Data reads are performed by asserting the Output Enable ( $\overline{OE}$ ) input and providing the required address on the address lines. Read data is accessible on I/O lines ( $I/O_0$  through  $I/O_{15}$ ). Byte accesses can be performed by asserting the required byte enable signal ( $\overline{BHE}$ ,  $\overline{BLE}$ ) to read either the upper byte or the lower byte of data from the specified address location.

All I/Os ( $I/O_0$  through  $I/O_{15}$ ) are placed in a high impedance state when the device is deselected ( $CE_1$  HIGH /  $CE_2$  LOW for dual chip enable device), or control signals are de-asserted ( $\overline{OE}$ ,  $\overline{BLE}$ ,  $\overline{BHE}$ ).

These devices also have a unique “Byte Power down” feature, where, if both the Byte Enables ( $\overline{BHE}$  and  $\overline{BLE}$ ) are disabled, the devices seamlessly switch to standby mode irrespective of the state of the chip enable(s), thereby saving power.

The CY62157H device is available in a Pb-free 48-ball VFBGA and 48-pin TSOP I packages. The logic block diagram is on page 2.

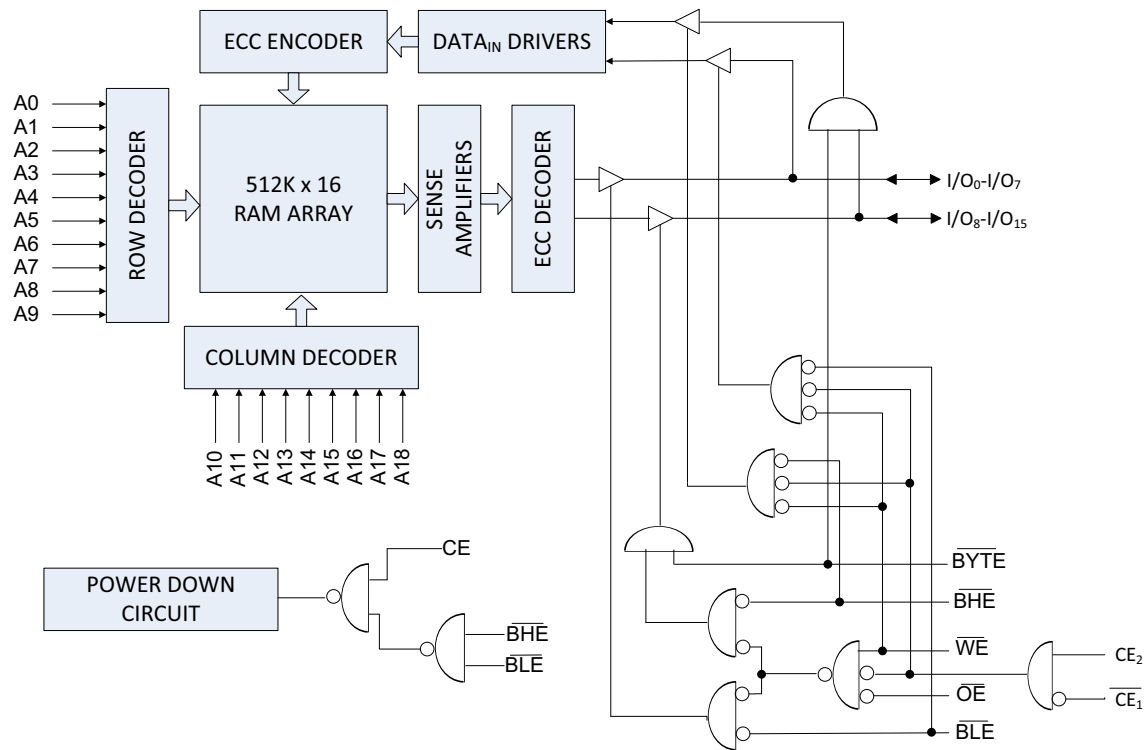
## Product Portfolio

Product	Features and Options (see the Pin Configurations section)	Range	V <sub>CC</sub> Range (V)	Speed (ns)	Power Dissipation			
					Operating I <sub>CC</sub> , (mA)		Standby, I <sub>SB2</sub> (μA)	
					f = f <sub>max</sub>			
					Typ <sup>[1]</sup>	Max	Typ <sup>[1]</sup>	Max
CY62157H30	Dual Chip Enable	Industrial	2.2 V–3.6 V	45	29	36	5.5	16

### Note

1. Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at  $V_{CC} = 3$  V (for  $V_{CC}$  range of 2.2 V–3.6 V),  $T_A = 25^\circ\text{C}$ .

## Logic Block Diagram



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## Pin Configurations

Figure 1. 48-ball VFBGA (6 × 8 × 1mm) pinout [2]

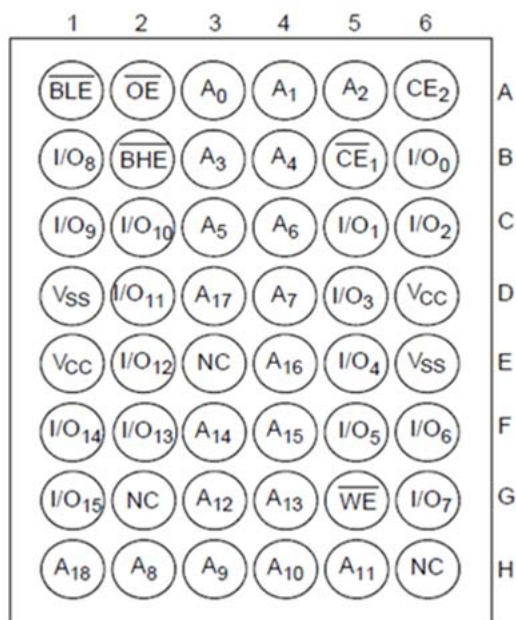
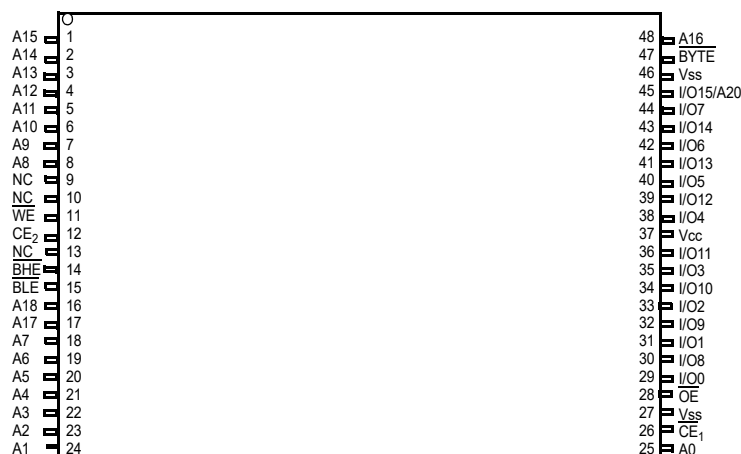


Figure 2. 48-pin TSOP I pinout (Dual Chip Enable) [2, 3]



### Notes

- NC pins are not connected internally to the die and are typically used for address expansion to a higher-density device. Refer to the respective datasheets for pin configuration.
- Tie the **BYTE** pin in the 48-pin TSOP I package to  $V_{CC}$  to use the device as a 1 M × 16 SRAM. The 48-pin TSOP I package can also be used as a 2 M × 8 SRAM by tying the **BYTE** signal to  $V_{SS}$ . In the 2 M × 8 configuration, Pin 45 is the extra address line A20, while **BHE**, **BLE**, and **I/O8** to **I/O14** pins are not used and can be left floating.

## Maximum Ratings

Exceeding maximum ratings may shorten the useful life of the device. User guidelines are not tested.

Storage temperature ..... -65 °C to + 150 °C

Ambient temperature  
with power applied ..... -55 °C to + 125 °C

Supply voltage  
to ground potential ..... -0.2 V to  $V_{CC} + 0.3$  V

DC voltage applied to outputs  
in High Z state <sup>[4]</sup> ..... -0.2 V to  $V_{CC} + 0.3$  V

DC input voltage <sup>[4]</sup> ..... -0.2 V to  $V_{CC} + 0.3$  V

Output current into outputs (LOW) ..... 20 mA

Static discharge voltage  
(MIL-STD-883, Method 3015) ..... >2001 V

Latch-up current ..... >140 mA

## Operating Range

Grade	Ambient Temperature	$V_{CC}$
Industrial	-40 °C to +85 °C	2.2 V to 3.6 V

## DC Electrical Characteristics

Over the Operating Range of -40 °C to 85 °C

Parameter	Description		Test Conditions		45 ns			Unit
					Min	Typ <sup>[5]</sup>	Max	
V <sub>OH</sub>	Output HIGH voltage	2.2 V to 2.7 V	V <sub>CC</sub> = Min, I <sub>OH</sub> = −0.1 mA		2	–	–	V
		2.7 V to 3.6 V	V <sub>CC</sub> = Min, I <sub>OH</sub> = −1.0 mA		2.4	–	–	
V <sub>OL</sub>	Output LOW voltage	2.2 V to 2.7 V	V <sub>CC</sub> = Min, I <sub>OL</sub> = 0.1 mA		–	–	0.4	V
		2.7 V to 3.6 V	V <sub>CC</sub> = Min, I <sub>OL</sub> = 2.1 mA		–	–	0.4	
V <sub>IH</sub>	Input HIGH voltage	2.2 V to 2.7 V	–		1.8	–	V <sub>CC</sub> + 0.3	V
		2.7 V to 3.6 V	–		2	–	V <sub>CC</sub> + 0.3	
V <sub>IL</sub>	Input LOW voltage <sup>[4]</sup>	2.2 V to 2.7 V	–		−0.3	–	0.6	V
		2.7 V to 3.6 V	–		−0.3	–	0.8	
I <sub>IX</sub>	Input leakage current		GND ≤ V <sub>IN</sub> ≤ V <sub>CC</sub>		−1	–	+1	μA
I <sub>OZ</sub>	Output leakage current		GND ≤ V <sub>OUT</sub> ≤ V <sub>CC</sub> , Output disabled		−1	–	+1	μA
I <sub>CC</sub>	V <sub>CC</sub> operating supply current		V <sub>CC</sub> = Max, I <sub>OUT</sub> = 0 mA, CMOS levels	f = f <sub>MAX</sub>	–	29.0	36.0	mA
				f = 1 MHz	–	7.0	9.0	mA
I <sub>SB1</sub> <sup>[6]</sup>	Automatic power down current – CMOS inputs; V <sub>CC</sub> = 2.2 to 3.6 V		CE <sub>1</sub> ≥ V <sub>CC</sub> − 0.2 V or CE <sub>2</sub> ≤ 0.2 V,  (BHE and BLE) ≥ V <sub>CC</sub> − 0.2 V, V <sub>IN</sub> ≥ V <sub>CC</sub> − 0.2 V, V <sub>IN</sub> ≤ 0.2 V, f = f <sub>max</sub> (address and data only),  f = 0 (OE, and WE), V <sub>CC</sub> = V <sub>CC(max)</sub>		–	5.5	16.0	μA
I <sub>SB2</sub> <sup>[6]</sup>	Automatic power down current – CMOS inputs V <sub>CC</sub> = 2.2 to 3.6 V		CE <sub>1</sub> ≥ V <sub>CC</sub> − 0.2 V or CE <sub>2</sub> ≤ 0.2 V,  (BHE and BLE) ≥ V <sub>CC</sub> − 0.2 V,  V <sub>IN</sub> ≥ V <sub>CC</sub> − 0.2 V or V <sub>IN</sub> ≤ 0.2 V, f = 0, V <sub>CC</sub> = V <sub>CC(max)</sub>	25 °C <sup>[7]</sup>	–	5.5	6.5	μA
				40 °C <sup>[7]</sup>	–	6.3	8.0	
				85 °C	–	12.0 <sup>[7]</sup>	16.0	

### Notes

4.  $V_{IL(\text{min})} = -2.0 \text{ V}$  and  $V_{IH(\text{max})} = V_{CC} + 2 \text{ V}$  for pulse durations of less than 20 ns.

5. Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at  $V_{CC} = 3 \text{ V}$  (for  $V_{CC}$  range of 2.2 V–3.6 V),  $T_A = 25 \text{ °C}$ .

6. Chip enables ( $\overline{CE}_1$  and  $\overline{CE}_2$ ) must be tied to CMOS levels to meet the  $I_{SB1} / I_{SB2} / I_{CCDR}$  spec. Other inputs can be left floating.

7. The  $I_{SB2}$  limits at 25 °C, 70 °C, 40 °C and typical limit at 85 °C are guaranteed by design and not 100% tested.

## Capacitance

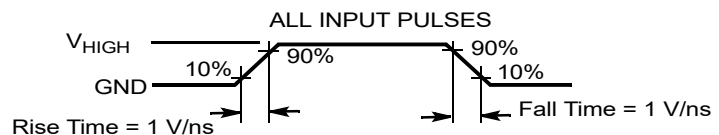
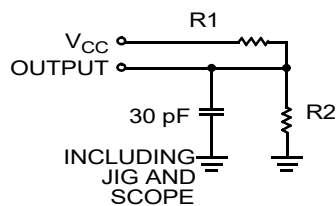
Parameter <sup>[8]</sup>	Description	Test Conditions	Max	Unit
$C_{IN}$	Input capacitance	$T_A = 25^\circ\text{C}$ , $f = 1\text{ MHz}$ , $V_{CC} = V_{CC(\text{typ})}$	10	pF
$C_{OUT}$	Output capacitance		10	pF

## Thermal Resistance

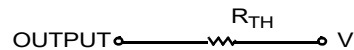
Parameter <sup>[8]</sup>	Description	Test Conditions	48-pin TSOP I	48-ball VFBGA	Unit
$\Theta_{JA}$	Thermal resistance (junction to ambient)	Still air, soldered on a 3 × 4.5 inch, two-layer printed circuit board	57.99	31.50	$^\circ\text{C/W}$
$\Theta_{JC}$	Thermal resistance (junction to case)		13.42	15.75	$^\circ\text{C/W}$

## AC Test Loads and Waveforms

Figure 3. AC Test Loads and Waveforms



Equivalent to: THÉVENIN EQUIVALENT



Parameters	2.5 V	3.0 V	Unit
R1	16667	1103	$\Omega$
R2	15385	1554	$\Omega$
$R_{TH}$	8000	645	$\Omega$
$V_{TH}$	1.20	1.75	V

### Note

8. Tested initially and after any design or process changes that may affect these parameters.

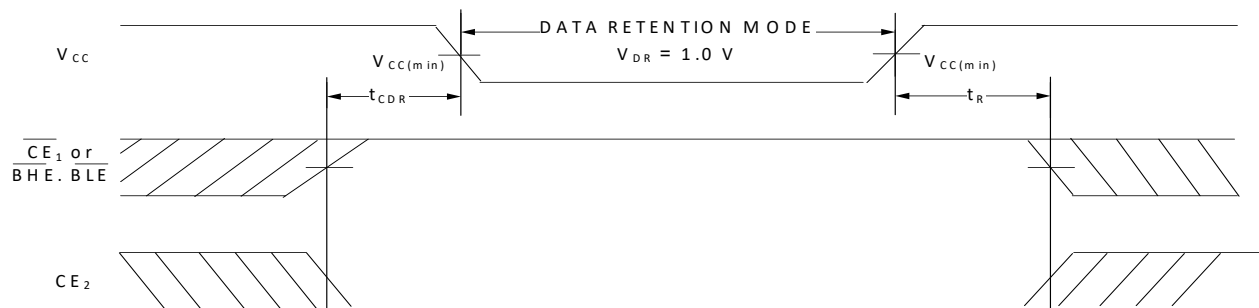
## Data Retention Characteristics

Over the Operating Range

Parameter	Description	Conditions	Min	Typ <sup>[9]</sup>	Max	Unit
$V_{DR}$	$V_{CC}$ for data retention		1	–	–	V
$I_{CCDR}$ <sup>[10, 11]</sup>	Data retention current	$2.2\text{ V} < V_{CC} \leq 3.6\text{ V}$ , $\overline{CE}_1 \geq V_{CC} - 0.2\text{ V}$ or $CE_2 \leq 0.2\text{ V}$ , $(\overline{BHE} \text{ and } \overline{BLE}) \geq V_{CC} - 0.2\text{ V}$ , $V_{IN} \geq V_{CC} - 0.2\text{ V}$ or $V_{IN} \leq 0.2\text{ V}$	–	5.5	16.0	$\mu\text{A}$
$t_{CDR}$ <sup>[12]</sup>	Chip deselect to data retention time		0	–	–	–
$t_R$ <sup>[13]</sup>	Operation recovery time		45	–	–	ns

## Data Retention Waveform

Figure 4. Data Retention Waveform<sup>[14]</sup>



### Notes

9. Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at  $V_{CC} = 3\text{ V}$  (for  $V_{CC}$  range of 2.2 V–3.6 V),  $T_A = 25^\circ\text{C}$ .
10. Chip enables ( $\overline{CE}_1$  and  $CE_2$ ) must be tied to CMOS levels to meet the  $I_{SB1}$  /  $I_{SB2}$  /  $I_{CCDR}$  spec. Other inputs can be left floating.
11.  $I_{CCDR}$  is guaranteed only after the device is first powered up to  $V_{CC(min)}$  and then brought down to  $V_{DR}$ .
12. Tested initially and after any design or process changes that may affect these parameters.
13. Full device operation requires linear  $V_{CC}$  ramp from  $V_{DR}$  to  $V_{CC(min)} \geq 100\text{ }\mu\text{s}$  or stable at  $V_{CC(min)} \geq 100\text{ }\mu\text{s}$ .
14.  $\overline{BHE}.\overline{BLE}$  is the AND of both  $\overline{BHE}$  and  $\overline{BLE}$ . Deselect the chip by either disabling the chip enable signals or by disabling both  $\overline{BHE}$  and  $\overline{BLE}$ .



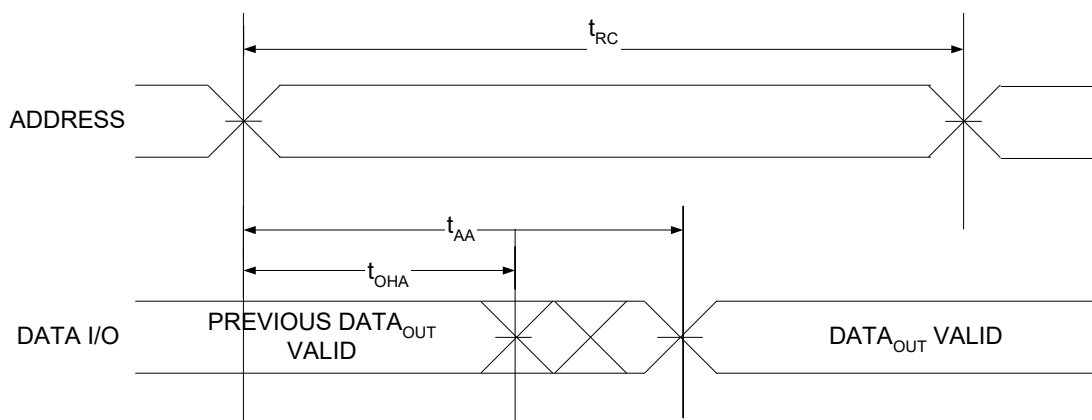
## Switching Characteristics

Parameter <sup>[15]</sup>	Description	45 ns		Unit
		Min	Max	
Read Cycle				
t <sub>RC</sub>	Read cycle time	45	–	ns
t <sub>AA</sub>	Address to data valid	–	45	ns
t <sub>OHA</sub>	Data hold from address change	10	–	ns
t <sub>ACE</sub>	$\overline{CE}_1$ LOW and CE <sub>2</sub> HIGH to data valid	–	45	ns
t <sub>DOE</sub>	$\overline{OE}$ LOW to data valid	–	22	ns
t <sub>LZOE</sub>	$\overline{OE}$ LOW to Low Z <sup>[16]</sup>	5	–	ns
t <sub>HZOE</sub>	$\overline{OE}$ HIGH to High Z <sup>[16, 17]</sup>	–	18	ns
t <sub>LZCE</sub>	$\overline{CE}_1$ LOW and CE <sub>2</sub> HIGH to Low-Z <sup>[16]</sup>	10	–	ns
t <sub>HZCE</sub>	$\overline{CE}_1$ HIGH and CE <sub>2</sub> LOW to High-Z <sup>[16, 17]</sup>	–	18	ns
t <sub>PU</sub>	$\overline{CE}_1$ LOW and CE <sub>2</sub> HIGH to power-up	0	–	ns
t <sub>PD</sub>	$\overline{CE}_1$ HIGH and CE <sub>2</sub> LOW to power-down	–	45	ns
t <sub>DBE</sub>	BLE / BHE LOW to data valid	–	45	ns
t <sub>LZBE</sub>	$\overline{BLE}$ / $\overline{BHE}$ LOW to Low-Z <sup>[16]</sup>	5	–	ns
t <sub>HZBE</sub>	$\overline{BLE}$ / $\overline{BHE}$ HIGH to High-Z <sup>[16, 17]</sup>	–	18	ns
Write Cycle <sup>[18, 19]</sup>				
t <sub>WC</sub>	Write cycle time	45	–	ns
t <sub>SCE</sub>	$\overline{CE}_1$ LOW and CE <sub>2</sub> HIGH to write end	35	–	ns
t <sub>AW</sub>	Address setup to write end	35	–	ns
t <sub>HA</sub>	Address hold from write end	0	–	ns
t <sub>SA</sub>	Address setup to write start	0	–	ns
t <sub>PWE</sub>	$\overline{WE}$ pulse width	35	–	ns
t <sub>BW</sub>	BLE / BHE LOW to write end	35	–	ns
t <sub>SD</sub>	Data setup to write end	25	–	ns
t <sub>HD</sub>	Data hold from write end	0	–	ns
t <sub>HZWE</sub>	$\overline{WE}$ LOW to High-Z <sup>[16, 17]</sup>	–	18	ns
t <sub>LZWE</sub>	$\overline{WE}$ HIGH to Low-Z <sup>[16]</sup>	10	–	ns

### Notes

15. Test conditions assume signal transition time (rise/fall) of 3 ns or less, timing reference levels of 1.5 V (for  $V_{CC} \geq 3$  V) and  $V_{CC}/2$  (for  $V_{CC} < 3$  V), and input pulse levels of 0 to 3 V (for  $V_{CC} \geq 3$  V) and 0 to  $V_{CC}$  (for  $V_{CC} < 3$  V). Test conditions for the read cycle use output loading shown in AC Test Loads and Waveforms section, unless specified otherwise.
16. At any temperature and voltage condition,  $t_{HZCE}$  is less than  $t_{LZCE}$ ,  $t_{HZBE}$  is less than  $t_{LZBE}$ ,  $t_{HZOE}$  is less than  $t_{LZOE}$ , and  $t_{HZWE}$  is less than  $t_{LZWE}$  for any device.
17.  $t_{HZOE}$ ,  $t_{HZCE}$ ,  $t_{HZBE}$ , and  $t_{HZWE}$  transitions are measured when the outputs enter a high impedance state.
18. The internal write time of the memory is defined by the overlap of  $\overline{WE} = V_{IL}$ ,  $\overline{CE}_1 = V_{IL}$ ,  $\overline{BHE}$  or  $\overline{BLE}$  or both =  $V_{IL}$ , and  $CE_2 = V_{IH}$ . All signals must be ACTIVE to initiate a write and any of these signals can terminate a write by going INACTIVE. The data input setup and hold timing must refer to the edge of the signal that terminates the write.
19. The minimum write cycle pulse width for Write Cycle No. 1 ( $\overline{WE}$  Controlled,  $\overline{OE}$  LOW) should be equal to the sum of  $t_{HZWE}$  and  $t_{SD}$ .

**Figure 5. Read Cycle No. 1 of CY62157H (Address Transition Controlled) [20, 21]**



20. The device is continuously selected.  $\overline{OE} = V_{LL}$ ,  $\overline{CE} = V_{LL}$ ,  $\overline{BHE}$  or  $\overline{BLE}$  or both =  $V_{LL}$ .

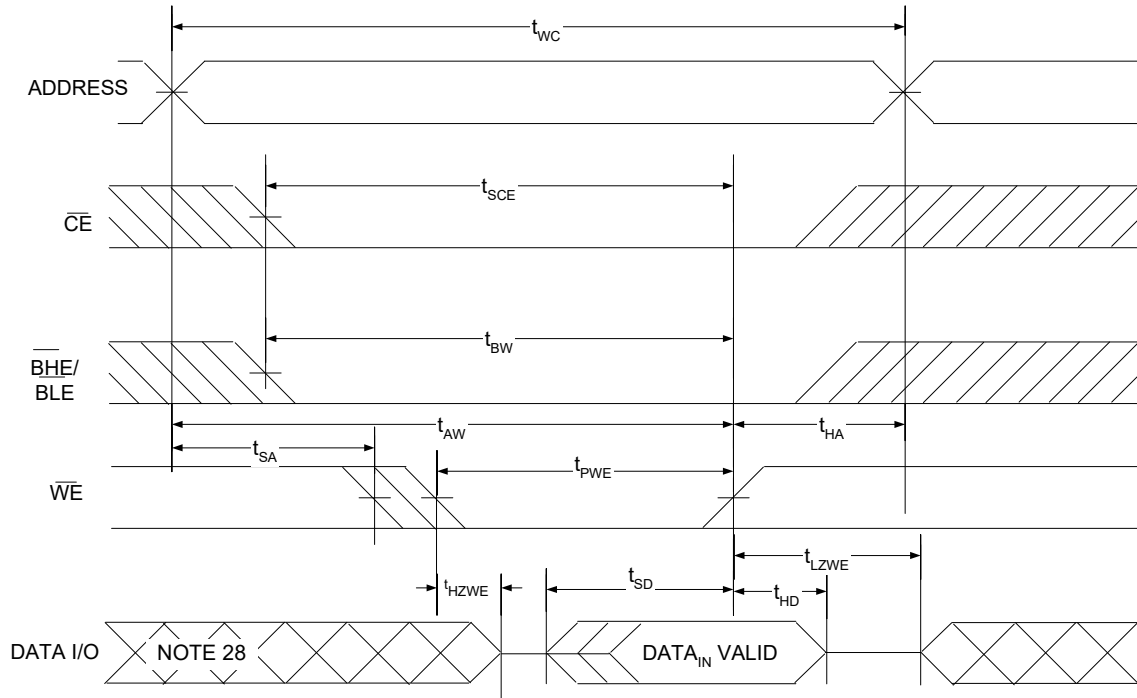
21.  $\overline{WE}$  is HIGH for read cycle.

22. For all dual chip enable devices,  $\overline{CE}$  is the logical combination of  $\overline{CE}_1$  and  $CE_2$ . When  $\overline{CE}_1$  is LOW and  $CE_2$  is HIGH,  $\overline{CE}$  is LOW; when  $\overline{CE}_1$  is HIGH or  $CE_2$  is LOW,  $\overline{CE}$  is HIGH.

23. Address valid prior to or coincident with  $\overline{\text{CE}}$  LOW transition.

## Switching Waveforms (continued)

**Figure 7. Write Cycle No. 1 ( $\overline{WE}$  Controlled,  $\overline{OE}$  LOW)** [24, 25, 26, 27]

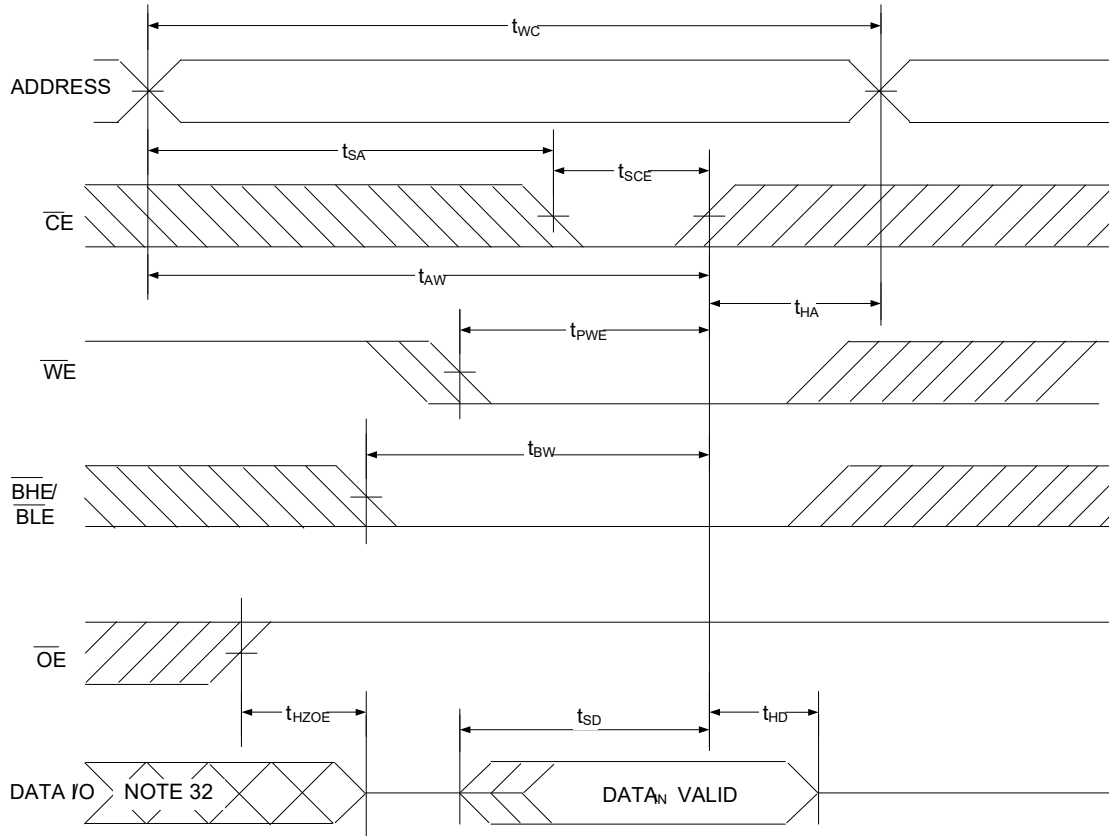


### Notes

24. For all dual chip enable devices,  $\overline{CE}$  is the logical combination of  $\overline{CE}_1$  and  $CE_2$ . When  $\overline{CE}_1$  is LOW and  $CE_2$  is HIGH,  $\overline{CE}$  is LOW; when  $\overline{CE}_1$  is HIGH or  $CE_2$  is LOW,  $\overline{CE}$  is HIGH.
25. The internal write time of the memory is defined by the overlap of  $\overline{WE} = V_{IL}$ ,  $\overline{CE}_1 = V_{IL}$ ,  $\overline{BHE}$  or  $\overline{BLE}$  or both =  $V_{IL}$ , and  $CE_2 = V_{IH}$ . All signals must be ACTIVE to initiate a write and any of these signals can terminate a write by going INACTIVE. The data input setup and hold timing must refer to the edge of the signal that terminates the write.
26. Data I/O is in high impedance state if  $\overline{CE} = V_{IH}$ , or  $\overline{OE} = V_{IH}$  or  $\overline{BHE}$ , and/or  $\overline{BLE} = V_{IH}$ .
27. The minimum write cycle pulse width for Write Cycle No. 1 ( $\overline{WE}$  Controlled,  $\overline{OE}$  LOW) should be equal to the sum of  $t_{HZWE}$  and  $t_{SD}$ .
28. During this period the I/Os are in output state. Do not apply input signals.

## Switching Waveforms (continued)

**Figure 8. Write Cycle No. 2 ( $\overline{\text{CE}}$  Controlled)** [29, 30, 31]



### Notes

29. For all dual chip enable devices,  $\overline{\text{CE}}$  is the logical combination of  $\overline{\text{CE}}_1$  and  $\text{CE}_2$ . When  $\overline{\text{CE}}_1$  is LOW and  $\text{CE}_2$  is HIGH,  $\overline{\text{CE}}$  is LOW; when  $\overline{\text{CE}}_1$  is HIGH or  $\text{CE}_2$  is LOW,  $\overline{\text{CE}}$  is HIGH.

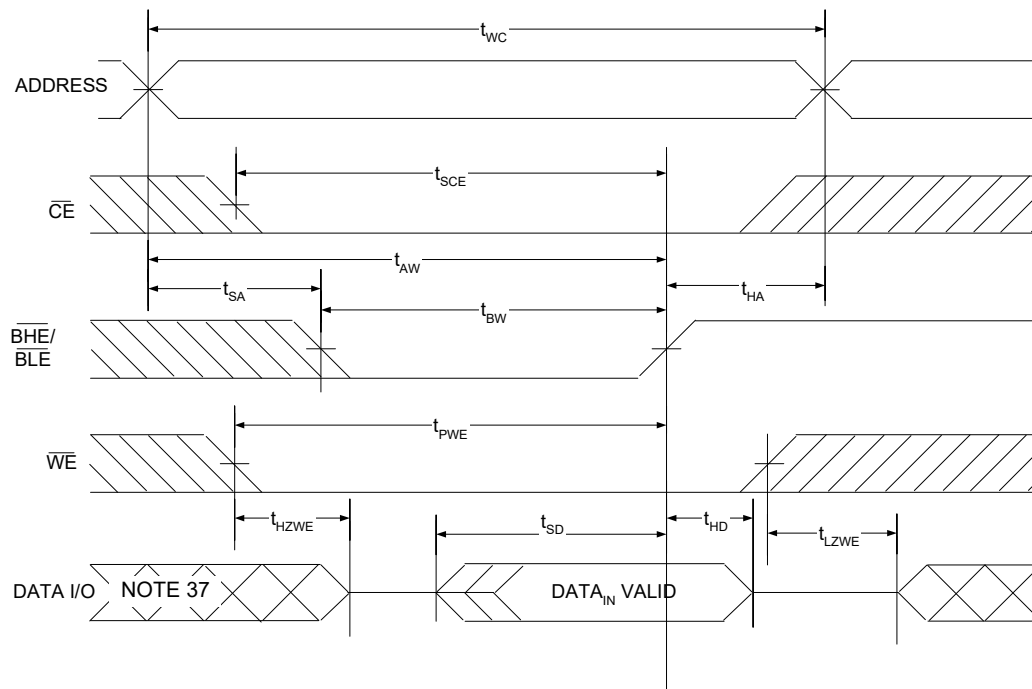
30. The internal write time of the memory is defined by the overlap of  $\overline{\text{WE}} = V_{IL}$ ,  $\overline{\text{CE}}_1 = V_{IL}$ ,  $\overline{\text{BHE}}$  or  $\overline{\text{BLE}}$  or both =  $V_{IL}$ , and  $\text{CE}_2 = V_{IH}$ . All signals must be ACTIVE to initiate a write and any of these signals can terminate a write by going INACTIVE. The data input setup and hold timing must refer to the edge of the signal that terminates the write.

31. Data I/O is in high impedance state if  $\overline{\text{CE}} = V_{IH}$ , or  $\overline{\text{OE}} = V_{IH}$  or  $\overline{\text{BHE}}$ , and/or  $\overline{\text{BLE}} = V_{IH}$ .

32. During this period the I/Os are in output state. Do not apply input signals.

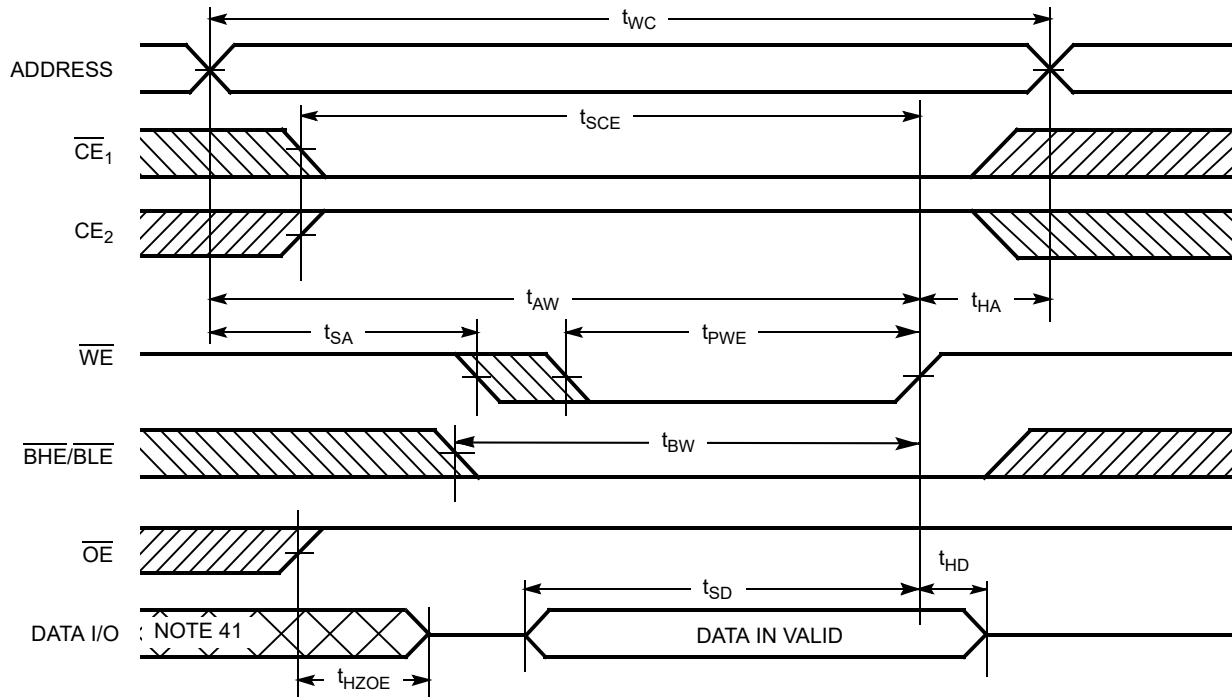
## Switching Waveforms (continued)

**Figure 9. Write Cycle No. 3 ( $\overline{\text{BHE}}/\overline{\text{BLE}}$  controlled,  $\overline{\text{OE}}$  LOW)** [33, 34, 35, 36]



### Notes

33. For all dual chip enable devices,  $\overline{\text{CE}}$  is the logical combination of  $\overline{\text{CE}}_1$  and  $\text{CE}_2$ . When  $\overline{\text{CE}}_1$  is LOW and  $\text{CE}_2$  is HIGH,  $\overline{\text{CE}}$  is LOW; when  $\overline{\text{CE}}_1$  is HIGH or  $\text{CE}_2$  is LOW,  $\overline{\text{CE}}$  is HIGH.
34. The internal write time of the memory is defined by the overlap of  $\overline{\text{WE}} = V_{\text{IL}}$ ,  $\overline{\text{CE}}_1 = V_{\text{IL}}$ ,  $\overline{\text{BHE}}$  or  $\overline{\text{BLE}}$  or both =  $V_{\text{IL}}$ , and  $\text{CE}_2 = V_{\text{IH}}$ . All signals must be ACTIVE to initiate a write and any of these signals can terminate a write by going INACTIVE. The data input setup and hold timing must refer to the edge of the signal that terminates the write.
35. Data I/O is in high impedance state if  $\overline{\text{CE}} = V_{\text{IH}}$ , or  $\overline{\text{OE}} = V_{\text{IH}}$  or  $\overline{\text{BHE}}$ , and/or  $\overline{\text{BLE}} = V_{\text{IH}}$ .
36. The minimum write cycle pulse width for Write Cycle No. 3 ( $\overline{\text{BHE}}/\overline{\text{BLE}}$  Controlled,  $\overline{\text{OE}}$  LOW) should be equal to the sum of  $t_{\text{HZWE}}$  and  $t_{\text{SD}}$ .
37. During this period the I/Os are in output state. Do not apply input signals.

**Switching Waveforms (continued)**
**Figure 10. Write Cycle No. 4 ( $\overline{WE}$  Controlled) [38, 39, 40]**

**Notes**

38. The internal write time of the memory is defined by the overlap of  $\overline{WE}$ ,  $\overline{CE}_1 = V_{IL}$ ,  $\overline{BHE}$  or  $\overline{BLE}$  or both =  $V_{IL}$ , and  $\overline{CE}_2 = V_{IH}$ . All signals must be ACTIVE to initiate a write and any of these signals can terminate a write by going INACTIVE. The data input setup and hold timing must refer to the edge of the signal that terminates the write.
39. Data I/O is high impedance if  $\overline{OE} = V_{IH}$ .
40. If  $\overline{CE}_1$  goes HIGH and  $\overline{CE}_2$  goes LOW simultaneously with  $\overline{WE} = V_{IH}$ , the output remains in a high impedance state.
41. During this period the I/Os are in output state. Do not apply input signals.

**Truth Table – CY62157H**

$\overline{CE}_1$	$CE_2$	$\overline{WE}$	$\overline{OE}$	$\overline{BHE}$	$\overline{BLE}$	Inputs/Outputs	Mode	Power
H	X <sup>[42]</sup>	X	X	X	X	High-Z	Deselect/Power-down	Standby ( $I_{SB}$ )
X <sup>[42]</sup>	L	X	X	X	X	High-Z	Deselect/Power-down	Standby ( $I_{SB}$ )
X <sup>[42]</sup>	X <sup>[42]</sup>	X	X	H	H	High-Z	Deselect/Power-down	Standby ( $I_{SB}$ )
L	H	H	L	L	L	Data Out ( $I/O_0$ – $I/O_{15}$ )	Read	Active ( $I_{CC}$ )
L	H	H	L	H	L	Data Out ( $I/O_0$ – $I/O_7$ ); High-Z ( $I/O_8$ – $I/O_{15}$ )	Read	Active ( $I_{CC}$ )
L	H	H	L	L	H	High Z ( $I/O_0$ – $I/O_7$ ); Data Out ( $I/O_8$ – $I/O_{15}$ )	Read	Active ( $I_{CC}$ )
L	H	L	X	L	L	Data In ( $I/O_0$ – $I/O_{15}$ )	Write	Active ( $I_{CC}$ )
L	H	L	X	H	L	Data In ( $I/O_0$ – $I/O_7$ ); High-Z ( $I/O_8$ – $I/O_{15}$ )	Write	Active ( $I_{CC}$ )
L	H	L	X	L	H	High-Z ( $I/O_0$ – $I/O_7$ ); Data In ( $I/O_8$ – $I/O_{15}$ )	Write	Active ( $I_{CC}$ )
L	H	H	L	X	X	Data Out ( $I/O_0$ – $I/O_7$ )	Read	Active ( $I_{CC}$ )
L	H	H	H	X	X	High-Z	Output disabled	Active ( $I_{CC}$ )
L	H	L	X	X	X	Data In ( $I/O_0$ – $I/O_7$ )	Write	Active ( $I_{CC}$ )

**Note**

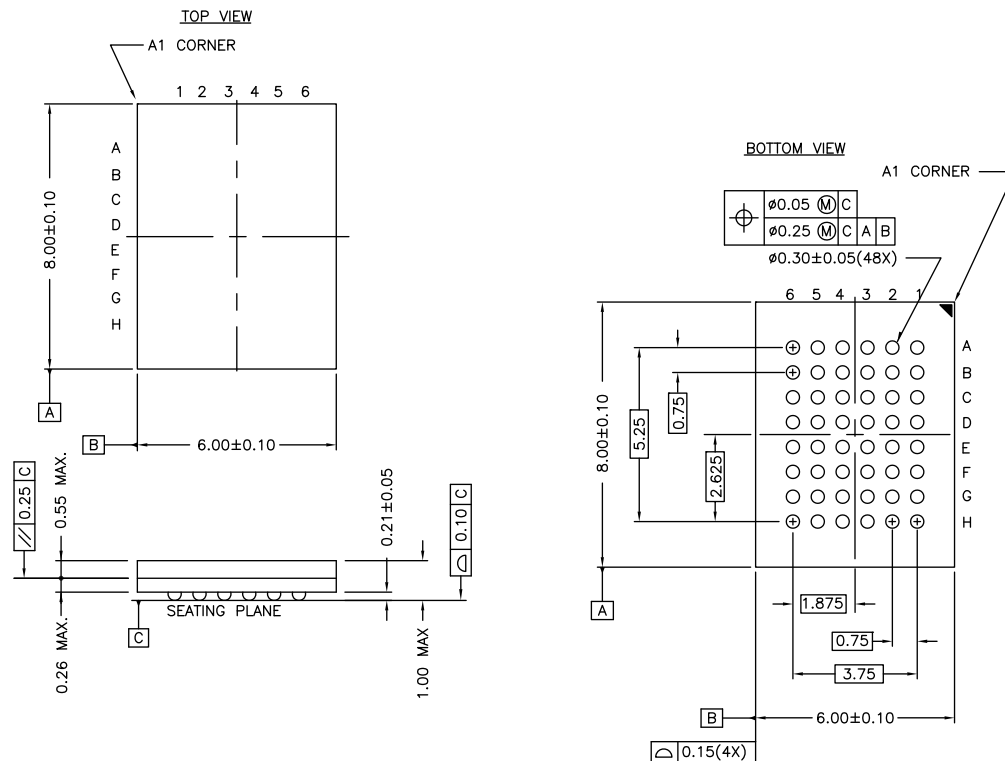
42. The 'X' (Don't care) state for the chip enables refer to the logic state (either HIGH or LOW). Intermediate voltage levels on these pins is not permitted.





## Package Diagrams

**Figure 11. 48-ball VFBGA (6 × 8 × 1.0 mm) Package Outline, 51-85150**



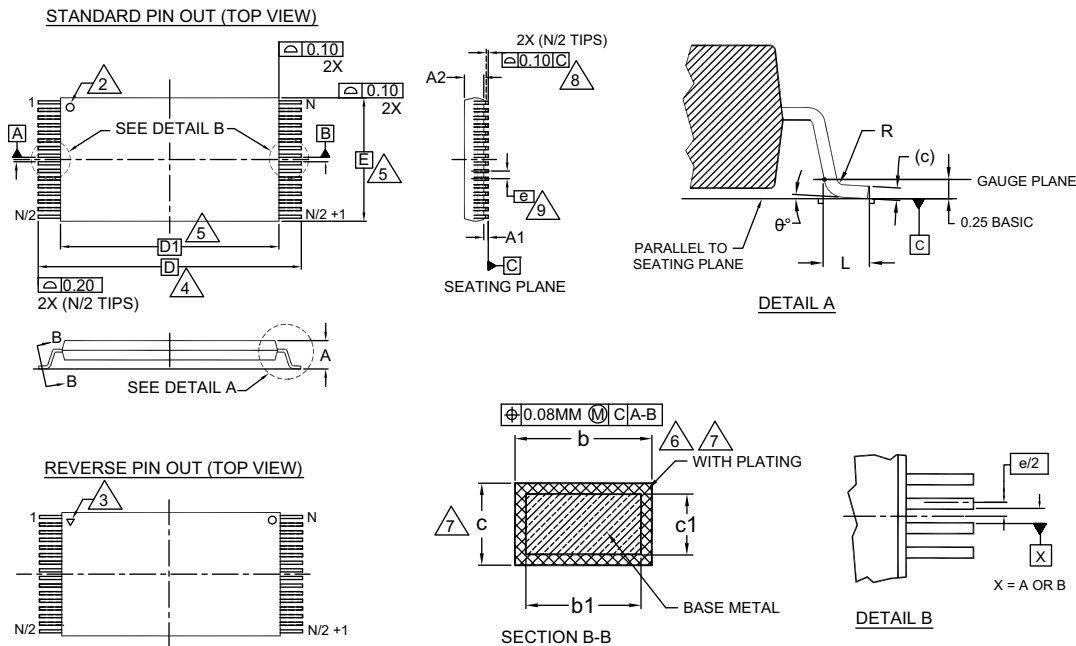
NOTE:

PACKAGE WEIGHT: See Cypress Package Material Declaration Datasheet (PMDD) posted on the Cypress web.

51-85150 \*H

## Package Diagrams (continued)

**Figure 12. 48-pin TSOP I (12 × 18.4 × 1.0 mm) Package Outline, 51-85183**



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	—	—	1.20
A1	0.05	—	0.15
A2	0.95	1.00	1.05
b1	0.17	0.20	0.23
b	0.17	0.22	0.27
c1	0.10	—	0.16
c	0.10	—	0.21
D	20.00 BASIC		
D1	18.40 BASIC		
E	12.00 BASIC		
e	0.50 BASIC		
L	0.50	0.60	0.70
θ	0°	—	8
R	0.08	—	0.20
N	48		

### NOTES:

1. DIMENSIONS ARE IN MILLIMETERS (mm).
2. PIN 1 IDENTIFIER FOR STANDARD PIN OUT (DIE UP).
3. PIN 1 IDENTIFIER FOR REVERSE PIN OUT (DIE DOWN): INK OR LASER MARK.
4. TO BE DETERMINED AT THE SEATING PLANE  $\square C$ . THE SEATING PLANE IS DEFINED AS THE PLANE OF CONTACT THAT IS MADE WHEN THE PACKAGE LEADS ARE ALLOWED TO REST FREELY ON A FLAT HORIZONTAL SURFACE.
5. DIMENSIONS D1 AND E DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION ON E IS 0.15mm PER SIDE AND ON D1 IS 0.25mm PER SIDE.
6. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF b DIMENSION AT MAX. MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD TO BE 0.07mm.
7. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.
8. LEAD COPLANARITY SHALL BE WITHIN 0.10mm AS MEASURED FROM THE SEATING PLANE.
9. DIMENSION "e" IS MEASURED AT THE CENTERLINE OF THE LEADS.
10. JEDEC SPECIFICATION NO. REF: MO-142(D)DD.

51-85183 \*F

## Acronyms

Acronym	Description
BHE	byte high enable
BLE	byte low enable
CE	chip enable
CMOS	complementary metal oxide semiconductor
I/O	input/output
OE	output enable
SRAM	static random access memory
VFBGA	very fine-pitch ball grid array
WE	write enable

## Document Conventions

### Units of Measure

Symbol	Unit of Measure
°C	Degrees Celsius
MHz	megahertz
μA	microamperes
μs	microseconds
mA	milliamperes
mm	millimeters
ns	nanoseconds
Ω	ohms
%	percent
pF	picofarads
V	volts
W	watts

## Document History Page

Document Title: CY62157H MoBL®, 8-Mbit (512K words × 16-bit) Static RAM with Error-Correcting Code (ECC) Document Number: 001-88316				
Rev.	ECN No.	Orig. of Change	Submission Date	Description of Change
*B	4983842	NILE	10/23/2015	Changed status from Preliminary to Final.
*C	5109716	NILE	01/27/2016	Updated <a href="#">DC Electrical Characteristics</a> : Changed minimum value of $V_{OH}$ parameter from 2.2 V to 2.4 V corresponding to $V_{CC}$ Operating Range “2.7 V to 3.6 V” and Test Condition “ $V_{CC} = \text{Min}$ , $I_{OH} = -1.0 \text{ mA}$ ”.
*D	5427485	VINI	09/06/2016	Updated <a href="#">Maximum Ratings</a> : Updated Note 4 (Replaced “2 ns” with “20 ns”). Updated <a href="#">DC Electrical Characteristics</a> : Changed minimum value of $V_{IH}$ parameter from 2.0 V to 1.8 V corresponding to the Operating Range “2.2 V to 2.7 V”. Updated <a href="#">Ordering Information</a> : Updated part numbers. Updated to new template. Completing Sunset Review.
*E	6063494	VINI	02/08/2018	Updated <a href="#">Package Diagrams</a> : spec 51-85183 – Changed revision from *D to *F. Updated to new template.

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